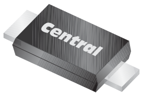
Material Composition Specification

SOD-323FL Case



Device average mass . . . . **5.0 mg**
Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.2%	0.06	Si	7440-21-3	1.2%	0.06	12,000
bond wire	copper	0.2%	0.01	Cu	7440-50-8	0.2%	0.01	2,000
leadframe	Cu alloy	48%	2.4	Cu	7440-50-8	47.92%	2.396	479,200
				Fe	7439-89-6	0.08%	0.004	800
encapsulation*	EMC GREEN	50.28%	2.514	silica	60676-86-0	38.8%	1.94	388,000
				epoxy resin	29690-82-2	5.0%	0.25	50,000
				phenol resin	9003-35-4	4.8%	0.24	48,000
				carbon black	1333-86-4	0.16%	0.008	1,600
				metal hydroxide	1309-42-8	1.52%	0.076	15,200
plating	matte tin	0.32%	0.016	Sn	7440-31-5	0.32%	0.016	3,200

*EMC GREEN molding compound is Halogen Free.

R0 (11-January 2012)